



QNHCHIP

QN4606

Product Specification

QN4606

30V Complementary MOSFET



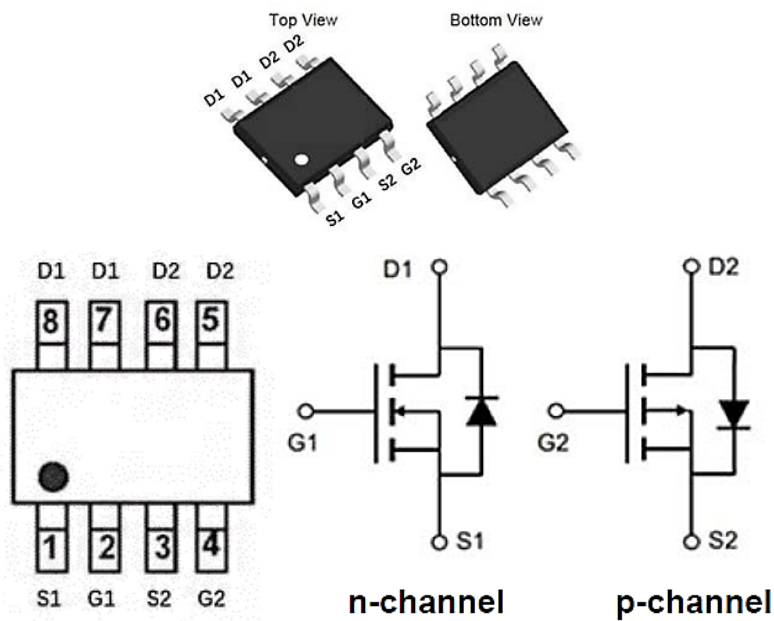
FEATURES

- N-Channel: 30V, 9A
 $R_{DS(ON)} < 21m\Omega @ V_{GS} = 10V$
 $R_{DS(ON)} < 33m\Omega @ V_{GS} = 4.5V$
- P-Channel: -30V, -7A
 $R_{DS(ON)} < 35m\Omega @ V_{GS} = -10V$
 $R_{DS(ON)} < 54m\Omega @ V_{GS} = -4.5V$
- Excellent Gate Charge x $R_{DS(ON)}$ Product(FOM)
- Very Low On-resistance $R_{DS(ON)}$
- Fast Switching Speed

Applications

- Battery Protection
- Load Switch
- Power Management

Pin Description



NO.	Symbol	Description
1	S1	SOURCE 1
2	G1	GATE 1
3	S2	SOURCE 2
4	G2	GATE 2
5	D2	DRAIN 2
6	D2	DRAIN 2
7	D1	DRAIN 1
8	D1	DRAIN 1



Absolute Maximum Ratings

(@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max. N-Channel	Max. P-Channel	Units
V_{DSS}	Drain-Source Voltage		30	-30	V
V_{GSS}	Gate-Source Voltage		± 20	± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ\text{C}$	9	-7	A
		$T_A = 100^\circ\text{C}$	6	-4.6	A
I_{DM}	Pulsed Drain Current note1		36	-28	A
E_{AS}	Single Pulsed Avalanche Energy note2		12	30	mJ
P_D	Power Dissipation	$T_A = 25^\circ\text{C}$	2.7	2.5	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		46.3	50	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150		$^\circ\text{C}$



N-Channel Electrical Characteristics

($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V$	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance ⁽²⁾	$V_{GS}=10V, I_D=5A$	-	16	21	m Ω
		$V_{GS}=4.5V, I_D=3A$	-	24	33	m Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V,$ $f=1.0\text{MHz}$	-	490	-	pF
C_{oss}	Output Capacitance		-	79	-	pF
C_{rss}	Reverse Transfer Capacitance		-	61	-	pF
Q_g	Total Gate Charge	$V_{DS}=15V, I_D=5A,$ $V_{GS}=10V$	-	5.2	-	nC
Q_{gs}	Gate-Source Charge		-	0.9	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	1.3	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15V, I_D=3A,$ $V_{GS}=10V, R_{REN}=3\Omega$	-	4.5	-	ns
t_r	Turn-on Rise Time		-	2.5	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	14.5	-	ns
t_f	Turn-off Fall Time		-	3.5	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	9	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	36	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=9A$	-	0.8	1.2	V

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. E_{AS} condition : $T_J=25^\circ\text{C}, V_{DD}=15V, V_G=10V, L=0.5\text{mH}, R_g=25\Omega, I_{AS}=7A$
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$



P-Channel Electrical Characteristics

($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30V, V_{GS}=0V,$	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	-1.5	-2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance(3)	$V_{GS}=-10V, I_D=-7A$	-	27	35	m Ω
		$V_{GS}=-4.5V, I_D=-4A$	-	38	54	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V,$ $f=1.0MHz$	-	982	-	pF
C_{oss}	Output Capacitance		-	135	-	pF
C_{rss}	Reverse Transfer Capacitance		-	109	-	pF
Q_g	Total Gate Charge	$V_{DS}=-15V, I_D=-4A,$ $V_{GS}=-10V$	-	10	-	nC
Q_{gs}	Gate-Source Charge		-	2	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	2.7	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=-15V, I_D=-7A,$ $V_{GS}=-10V,$ $R_{GEN}=2.5\Omega$	-	11	-	ns
t_r	Turn-on Rise Time		-	19	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	45	-	ns
t_f	Turn-off Fall Time		-	26	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-7	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-28	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=-7A$	-	-0.8	-1.2	V

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. E_{AS} condition : $T_J=25^{\circ}\text{C}, V_{DD}=-15V, V_G=-10V, L=0.5mH, R_g=25\Omega, I_{AS}=-11A$
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$



Typical Performance Characteristics-N

Figure 1: Output Characteristics

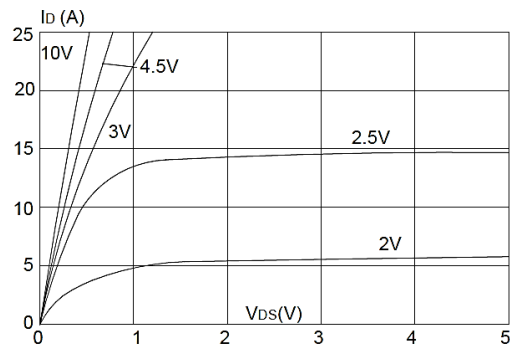


Figure 2: Typical Transfer Characteristics

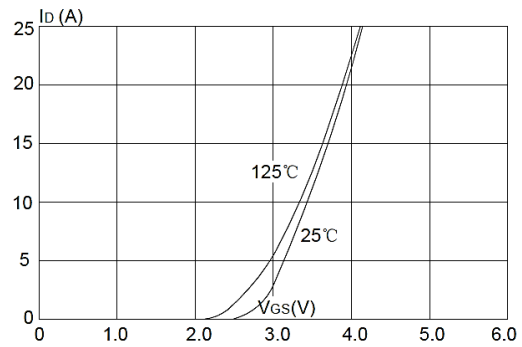


Figure 3: On-resistance vs. Drain Current

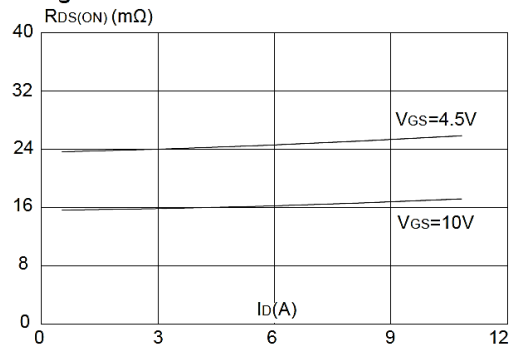


Figure 4: Body Diode Characteristics

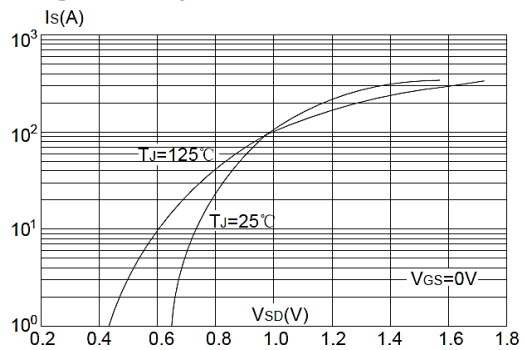


Figure 5: Gate Charge Characteristics

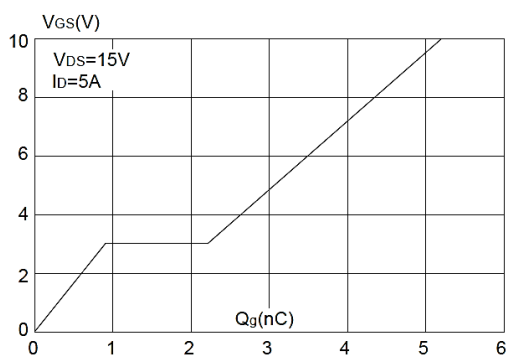


Figure 6: Capacitance Characteristics

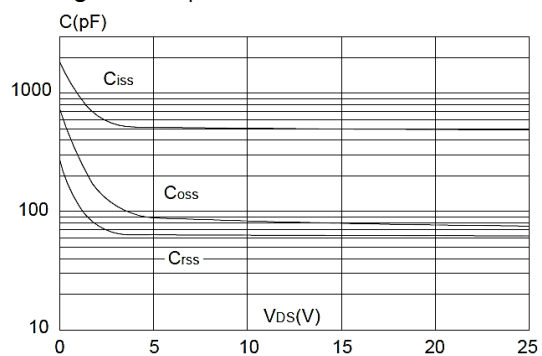


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

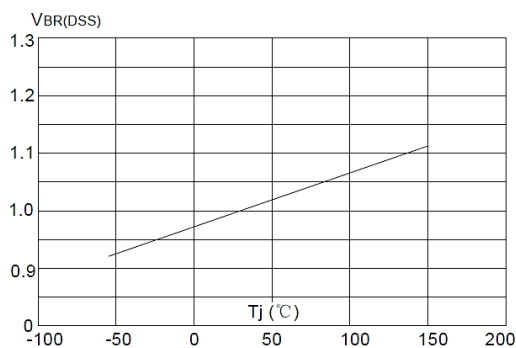


Figure 8: Normalized on Resistance vs. Junction Temperature

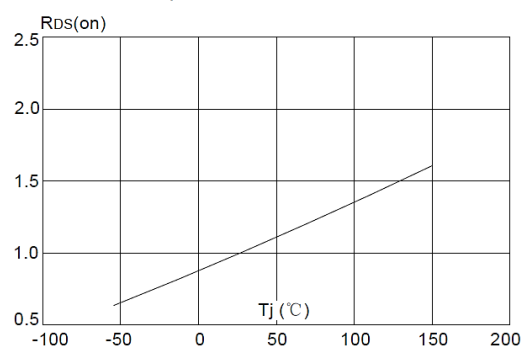




Figure 9: Maximum Safe Operating Area

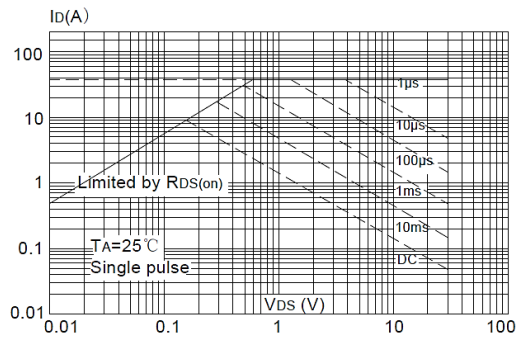


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

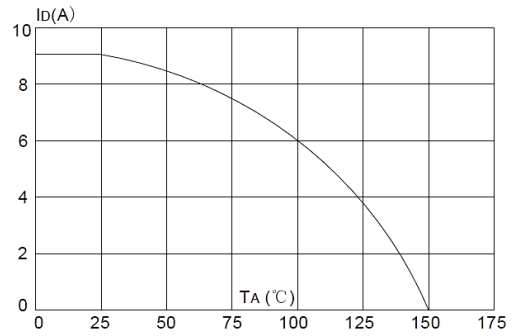
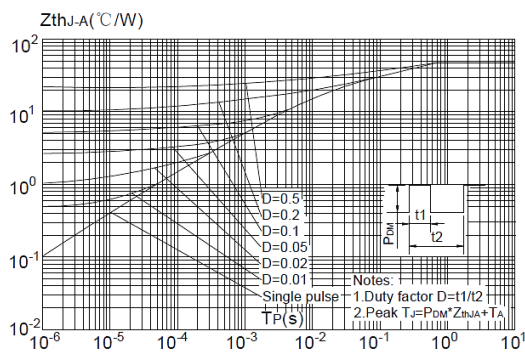


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient





Test Circuit-N

Figure1:Gate Charge Test Circuit & Waveform

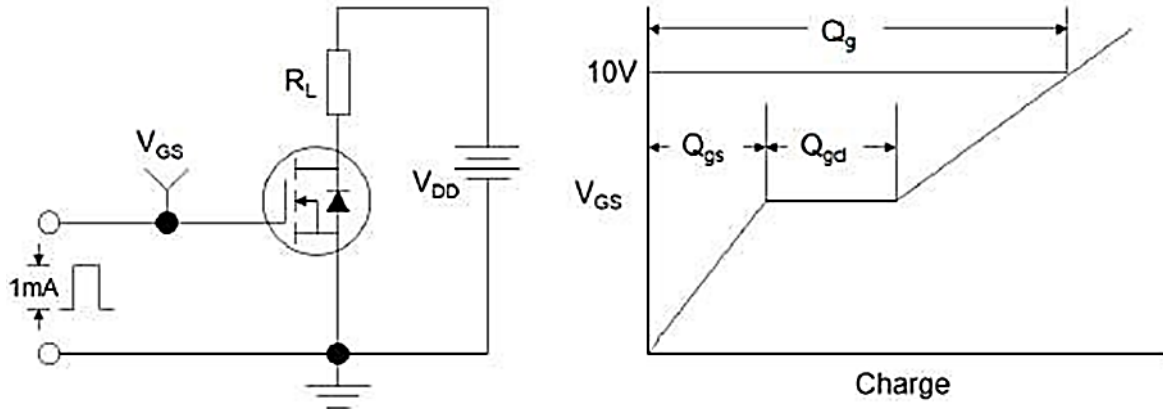


Figure 2: Resistive Switching Test Circuit & Waveforms

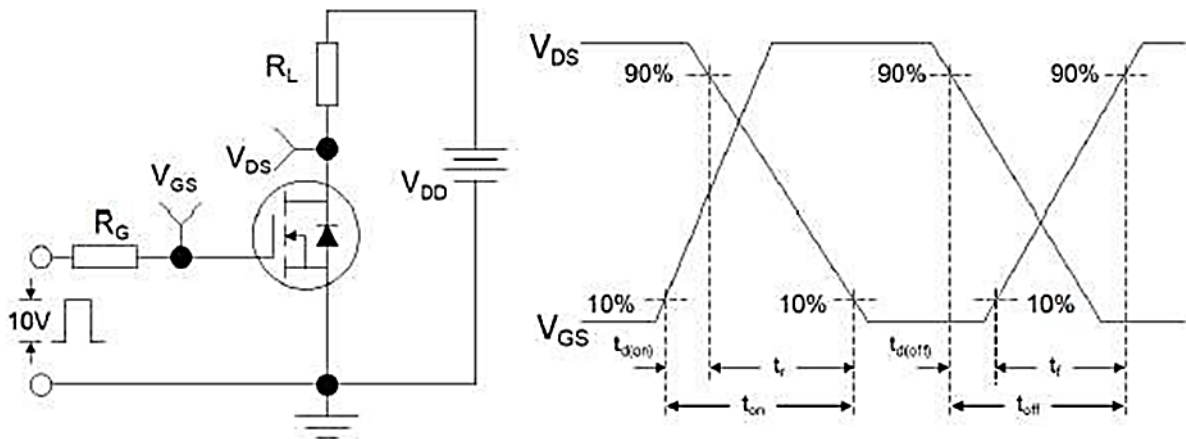
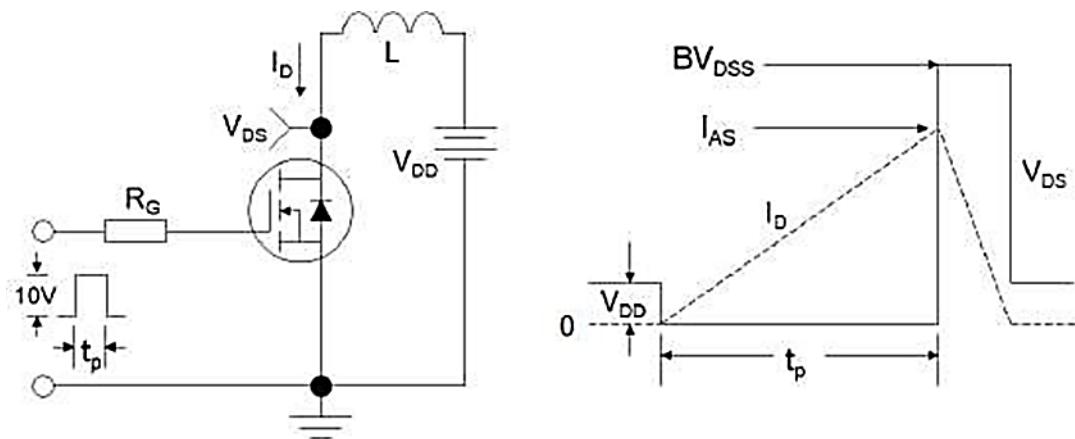


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms





Typical Performance Characteristics-P

Figure 1: Output Characteristics

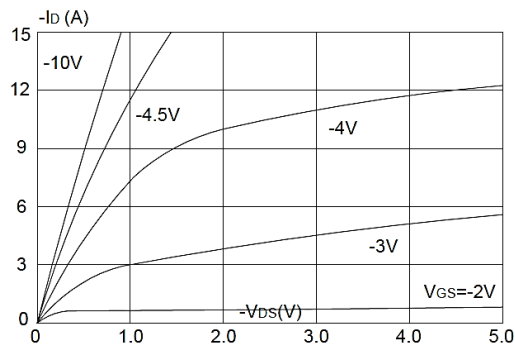


Figure 2: Typical Transfer Characteristics

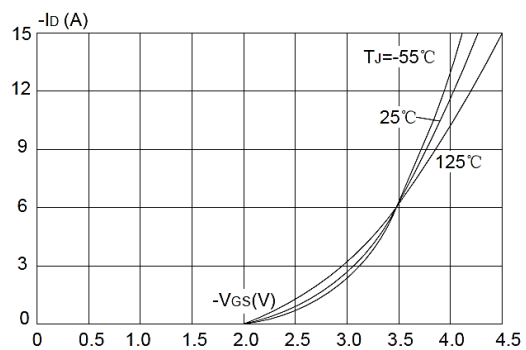


Figure 3: On-resistance vs. Drain Current

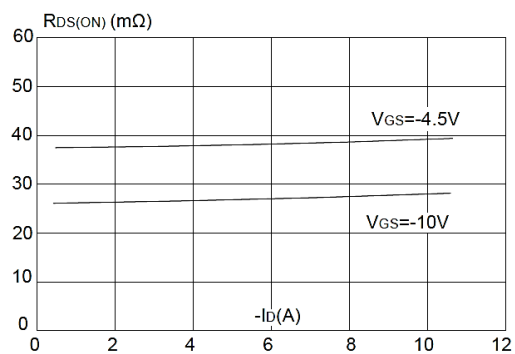


Figure 4: Body Diode Characteristics

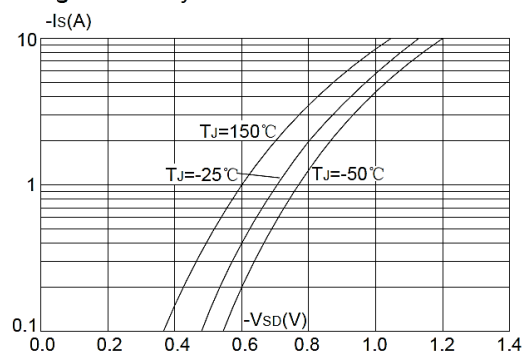


Figure 5: Gate Charge Characteristics

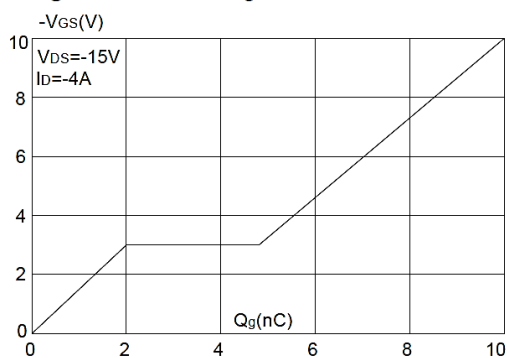


Figure 6: Capacitance Characteristics

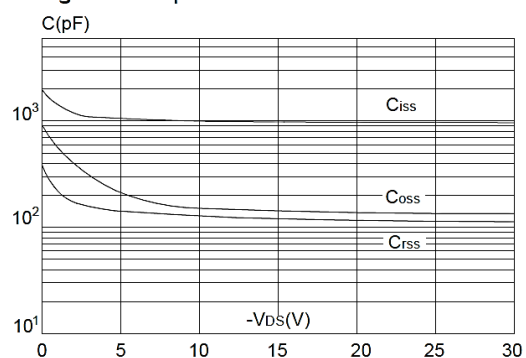


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

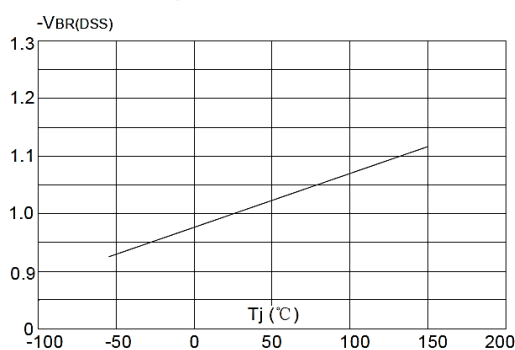


Figure 8: Normalized on Resistance vs. Junction Temperature

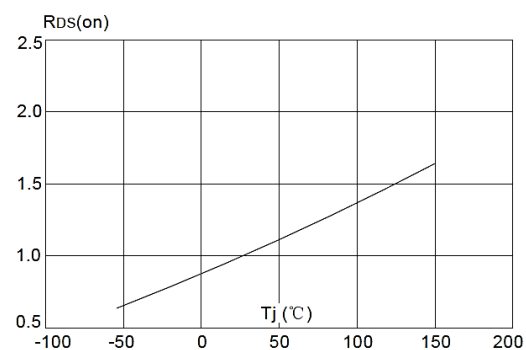




Figure 9: Maximum Safe Operating Area

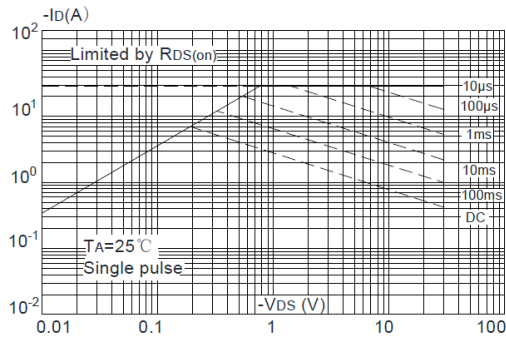


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

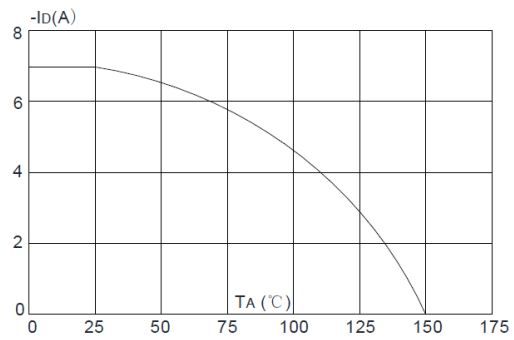
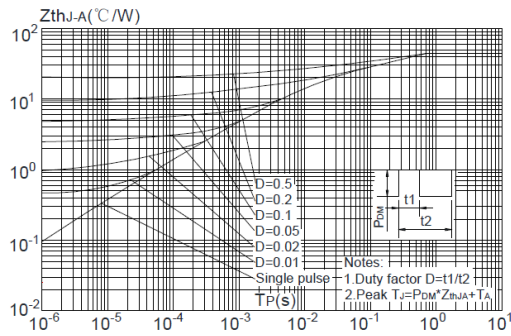


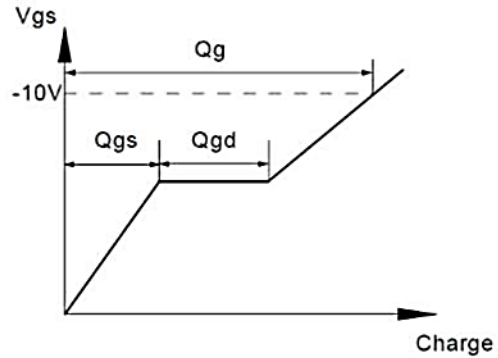
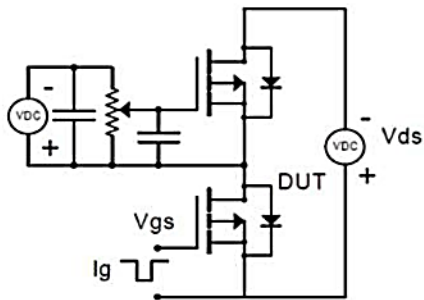
Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



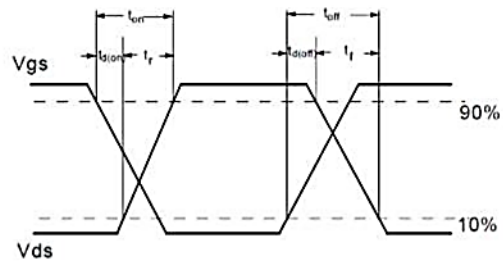
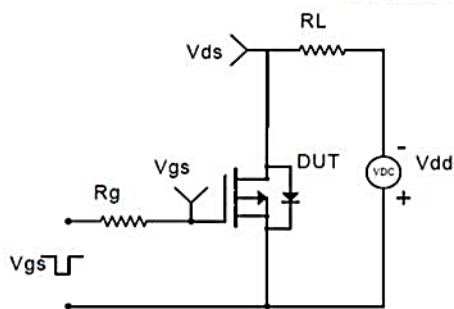


Test Circuit-P

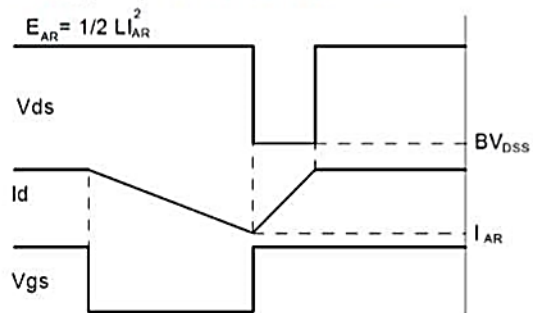
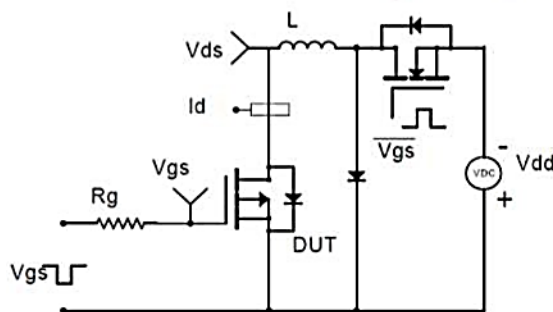
Gate Charge Test Circuit & Waveform



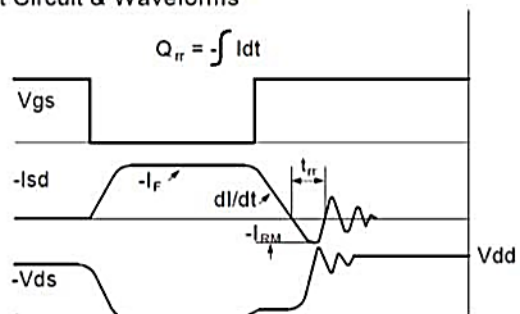
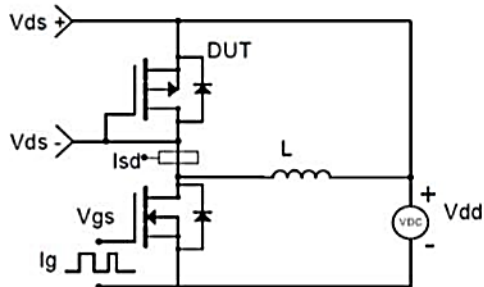
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



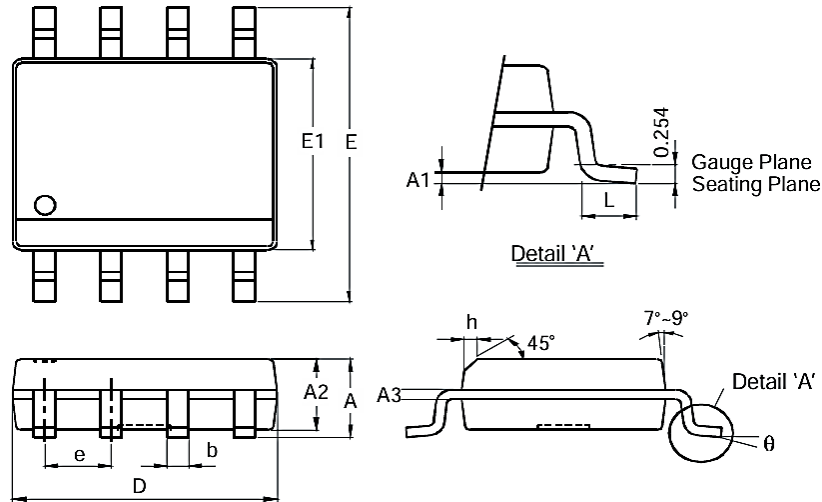
Diode Recovery Test Circuit & Waveforms





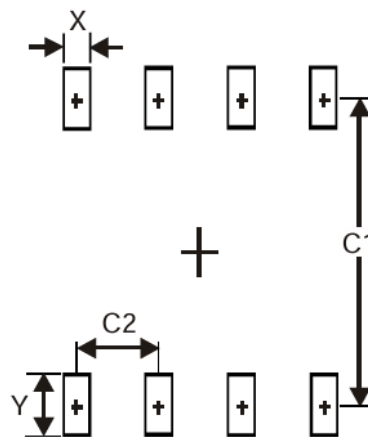
Package Mechanical Data

SOP-8



Dim	Min(mm)	Max(mm)
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°

suggested Pad Layout



Dimensions	Value(mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27



Ordering information

Order Code	Package	Channel	V _{DS} (V)	I _D (A)	R _{DS(ON)} (m Ω)	
QN4606	SOP-8	N-Channel	30	9	V _{GS} =10V	< 21
					V _{GS} =4.5V	< 33
		P-Channel	-30	-7	V _{GS} =-10V	< 35
					V _{GS} =-4.5V	< 54